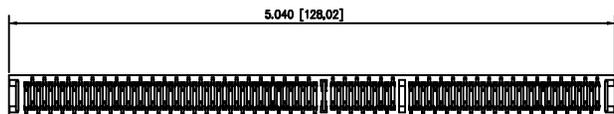
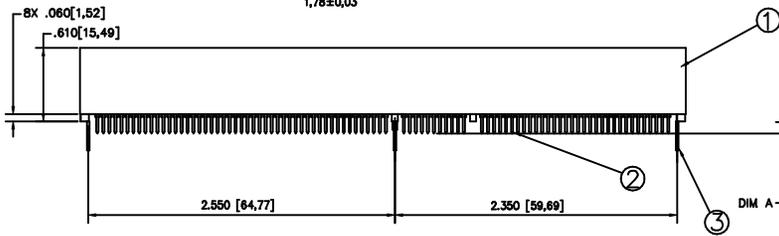
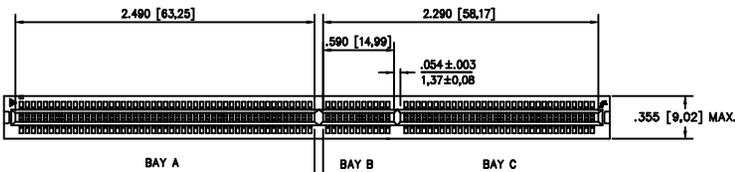
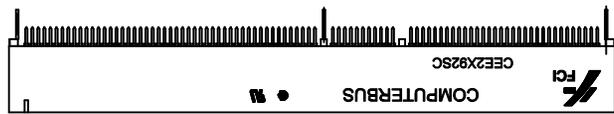
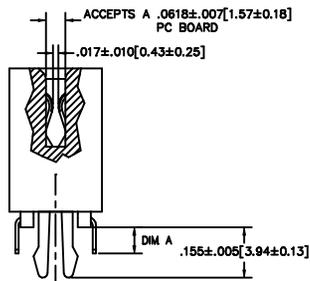


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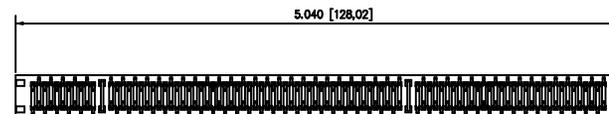
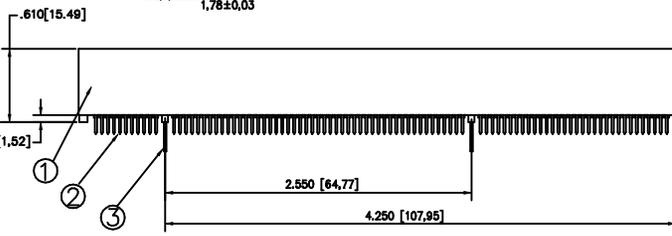
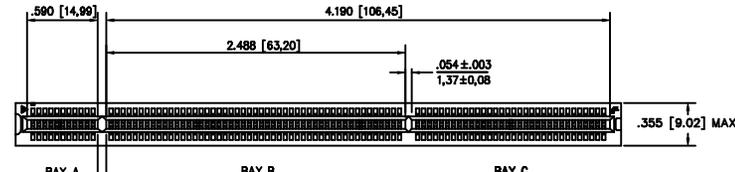
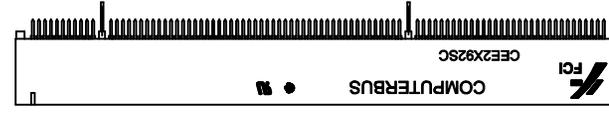


CEE2X92SC-V35Z_W
 CEE2X92SC-V54Z_W CONNECTOR SHOWN
 CEE2X92SC-V83Z_W
 FOR 5V/64-BIT APPLICATION



ITEM	DESCRIPTION	QTY	MATERIAL	FINISH
⑤	CLIP	3	STAINLESS 304	UNPLATED
②	CONTACT	184	PHOSPHOR BRONZE	AU/PD-NI
①	HOUSING	1	PCT 30% G/F	WHITE

sheet index
 revision sheet

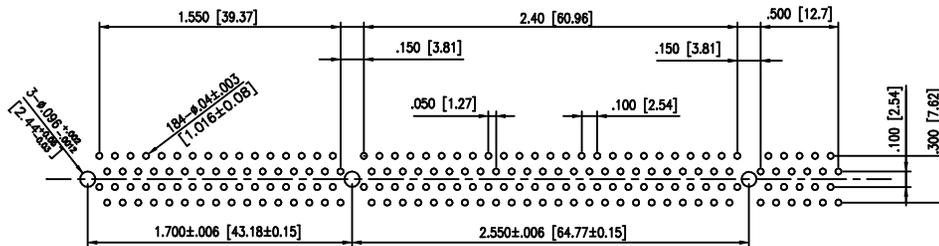


CEE2X92SC-V33Z_W
 CEE2X92SC-V60Z_W CONNECTOR SHOWN
 CEE2X92SC-V83Z_W
 FOR 3.3V/64-BIT APPLICATION

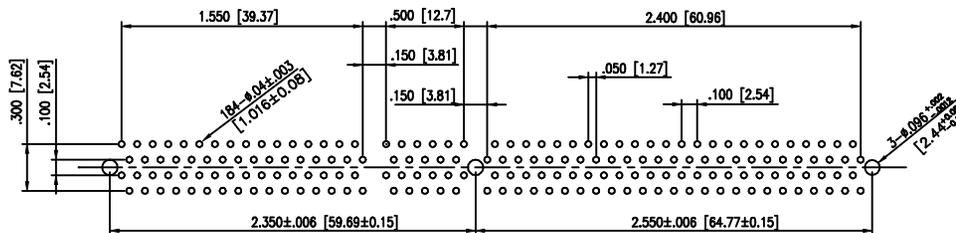
mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com		
itr	ecn no	dr	date	linear	.0 ± .10 [2,5]	projection	title	
c								.00 ± .020 [0,5]
				angles	ANGLES ±1°	product family	code	
				dr	JASON HSU	12/18/01	PCI	TWN
				enr	JASON HSU	12/18/01	size	sheet
				chr	JASON HSU	12/18/01	dwg no	2 of
				appd	JAMES HSU	12/18/01	57400	
				scale	1 : 1			
				sheet	A3			

This data indicates recommended dimensions for manufacturing. It does not constitute a contract. It is subject to change without notice. FCI reserves the right to change dimensions without notice.

All data subject to change. Dimensions in inches are given in preference to millimeters. Dimensions in millimeters are given in preference to inches.



RECOMMENDED PCB LAYOUT (TOP VIEW)
FOR 3.3V/64-BIT APPLICATION



RECOMMENDED PCB LAYOUT (TOP VIEW)
FOR 5V/64-BIT APPLICATION

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecr no	dr	date	linear	.0 ± .10 [2.5]	projection	title
c					.00 ± .020 [0.5]		PCI 64 BIT CARD EDGE CONNECTOR CEE2X92S_-V_Z_W
				angles	.000 ± .005 [0.13]		
					ANGLES ±1°	INCH/MM	product family PCI
		dr	JASON HSU	12/18/01		size	dwg no
		enr	JASON HSU	12/18/01		code	TWN
		chr	JASON HSU	12/18/01	scale	57400	sheet
		appd	JAMES HSU	12/18/01	1 : 1	4 of	
sheet	revision						
index	sheet						

TABLE 1 - BAY CONFIGURATIONS				TOTAL NUMBER OF CONTACTS	TAIL LENGTH DIM. A INCH±.01 [MM±0.25]	POST LENGTH DIM. B INCH±.01 [MM±0.25]
BURNDY CATALOG NO.	NUMBER OF CONTACT PAIRS					
	BAY A	BAY B	BAY C	REQ'D		
CEE2X92S*-V33Z**	11	49	32	184	.100 [2.54]	.180 [4.58]
CEE2X92S*-V35Z**	49	11	32	184	.100 [2.54]	.180 [4.58]
CEE2X92S*-V50Z**	11	49	32	184	.118 [3.0]	.180 [4.58]
CEE2X92S*-V58Z**	49	11	32	184	.118 [3.0]	.180 [4.58]
CEE2X92S*-V83Z**	11	49	32	184	.140 [3.56]	.220 [5.59]
CEE2X92S*-V85Z**	49	11	32	184	.140 [3.56]	.220 [5.59]

NOTES UNLESS OTHERWISE SPECIFIED.

- INTERPRET THIS DRAWING IN ACCORDANCE WITH ANSI Y14.5M-1982
- SEE SHEET 3, 4 FOR RECOMMENDED MATING DAUGHTERCARD AND MOTHERBOARD LAYOUTS.
- MATING DAUGHTERBOARD MATERIAL:
PC BOARD FR-4 WITH 1 OZ[28.35 GRAMS] MIN. COPPER PADS
PAD PLATING 30 MICROINCHES [0.76 MICRONS] MIN. GOLD PER MIL-G-45204. TYPE 1 CLASS 1, GRADE C OVER 100 MICROINCHES[2.54 MICRONS] MIN. NICKEL PER QQ-N-290

MATERIALS

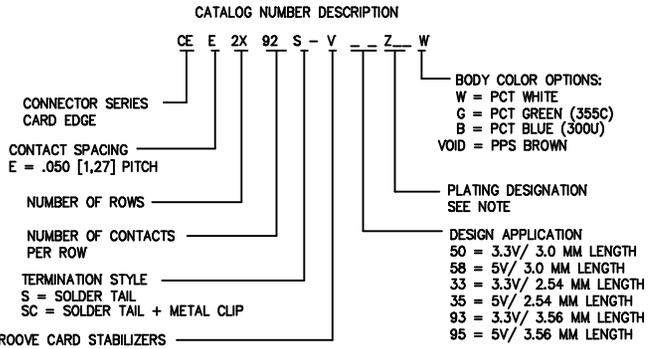
BODY - HIGH TEMPERATURE THERMOPLASTIC [PCT]. RATED UL 94V-0, COLOR WHITE.
CONTACTS - COPPER ALLOY.
CLIPS - STAINLESS STEEL.

FINISH CONTACTS

Z14 PLATING GOLD FLASH OVER 40 MICROINCHES (1.02 MICRONS) PALLADIUM-NICKEL OVER NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES (2.54 MICRONS) SOLDER OVER NICKEL UNDERPLATED ON SOLDER TAILS.
Z51 PLATING GOLD FLASH OVER 15 MICROINCHES [0.38 MICRONS] PALLADIUM-NICKEL OVER NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES (2.54 MICRONS) SOLDER OVER NICKEL UNDERPLATED ON SOLDER TAILS.
Z52 PLATING GOLD FLASH OVER NICKEL UNDERPLATE IN CRITICAL CONTACT AREA AND 100 MICROINCHES (2.54 MICRONS) SOLDER OVER NICKEL UNDERPLATE ON SOLDER TAILS.

PERFORMANCE CHARACTERISTICS :

CONTACT RESISTANCE : MIL-STD-1344. METHOD 3002.1. 30 MILLIOHMS. MAX. INITIAL 10 MILLOHMS MAX. INCREASE THROUGH TESTING. (LOW SIGNAL LEVEL)
CURRENT RATING : 1 AMPERE. 86F(30°) RISE ABOVE AMBIENT.
CONTACT NORMAL FORCE : 1.76 OZ FORCE (0.49 NEWTONS) MINIMUM END OF LIFE.
DURABILITY : 100 MATING CYCLES WITHOUT PHYSICAL DAMAGE . OR EXCEEDING LOW LEVEL CONTACT RESISTANCE REQUIREMENT
WHEN MATED WITH RECOMMENDED CARD EDGE.
INSULATION RESISTANCE : MIL-STD-202. METHOD 302. CONDITION B. 1000 MEGOHMS MINIMUM.
OPERATING TEMPERATURE : -40F TO 221F(-40C TO 105C)
THERMAL SHOCK : MIL-STD-202. METHOD 1003.1 -67F TO 185F[155C TO 85C] 5 CYCLES.
CAPACTANCE : 2 PICOFARADS MAXIMUM AT 1 MEGAHERTZ
MATING FORCE : MIL-STD-1344. METHOD 2013.1. 6 OZ.(1.67 NEWTONS) MAX. AVERAGE PER OPPOSING PAIR USING STEEL GAUGE PER MIL-STD C--21097 EXCEPT .062(1.57) THICK WITH 20° LEAD-IN CHAMFER ANGLE.
CONNECTOR IS COMPATAIBLE WITH WAVE SOLDERING AND VAPOR PHASE SOLDERING TECHNIQUES.
CONNECTOR INSTALLATION FORCE 15 LBS [66.76 NEWTONS] MAX.



mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.0 ± .10 [2.5]	projection	 title PCI 64 BIT CARD EDGE CONNECTOR CEE2X92S_-V_Z_W
c					.00 ± .020 [0.5]	INCH/MM	
				angles	.000± .005 [0.13]	← →	product family PCI
		dr	JASON HSU 12/18/01		ANGLES ±1°		code
		enr	JASON HSU 12/18/01			scale	TWN
		chr	JASON HSU 12/18/01			1 : 1	sheet
		appd	JAMES HSU 12/18/01			A3	5 of 5
sheet index	revision sheet						